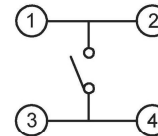
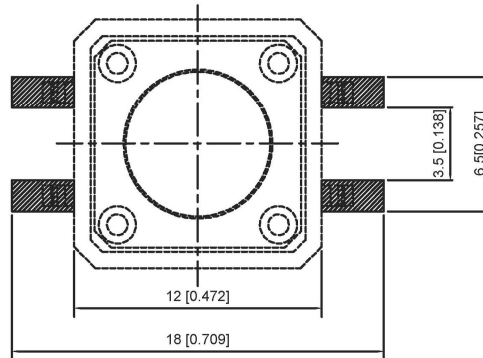
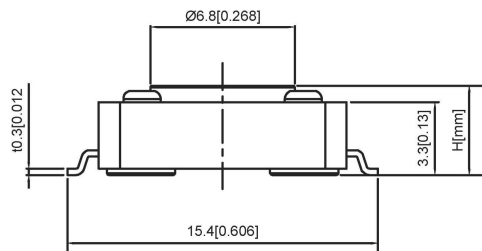


CIRCUIT DIAGRAM



Code-x	H	Code-x	H
A	4.3	O	11.0
B	4.5	P	11.5
C	5.0	Q	12
D	5.5	R	12.5
E	6.0	S	13.0
F	6.5	T	13.5
G	7.0	U	14.0
H	7.5	V	15.0
I	8.0	W	15.5
J	8.5	X	16
K	9.0	Y	17
L	9.5	Z	18
M	10.0	19	19
N	10.5		

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating: 50mA, 12V DC
Contact Resistance: 100mΩ max
Insulation Resistance: 100mΩ min. 500V DC
Dielectric Strength: 250V AC/1minute
Travel: 0.25mm
Operating Temp: -30°C~+85°C
Storage Temp: -30°C~+80°C

PAPT NO	TS-1103S-X-X
Operating Force	B:160gf C:260gf
Height	Code-x

ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	4	4	Brass (0.30t)	Plating silvering	
④	Contact	1	1	F.ag/Sus	Natural	
③	Base	1	1	Pa46		
②	Cover	1	1	Spcc	Plating Nickel	
①	Keystake	1	1	Pa46		

REVISIONS					UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE:		
ΔX					units: mm			VIEW:	TACT SWITCH		
ΔX					tolerance: X.X ±0.2mm	DWN	DATE		PART NO.:		
ΔX					X.XX ±0.1mm	CHKD	DATE	UNIT: mm/in	DWG NO		
MARK	DESCRIPTION	DATE	REVISED	APPROVED	X.XXX ±0.05mm	APPD	DATE	SIZE: A4	TS-1103S-X-X		
						DONG GUAN XI BANG ELECTRONIC CO., LTD			WEIGHT	SHEET	REVISION
									1.0g	1/1	A0